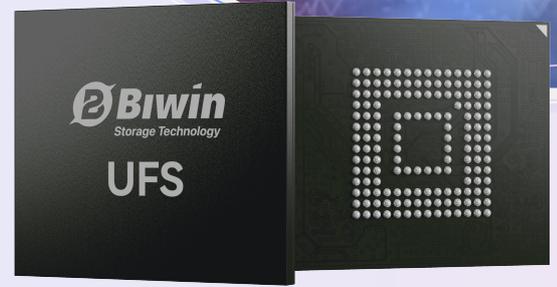




# UFS 2.2

BIWIN UFS 2.2 offers sequential read and write speeds up to 1000 MB/s and 800 MB/s, with capacities up to 512 GB.

This solution is widely used in smartphones, tablets, smart cameras, AR/VR, smart vehicles, drones, and more.



## Key Features

### High-Speed Read/Write with Smooth Data Transfer

The BIWIN UFS 2.2 uses an advanced differential serial interface and adheres to the JEDEC standard, resulting in significant improvements in read and write speeds. This reduces system boot times, application load times, and large file transfer delays, providing a smooth and uninterrupted experience in high-speed data transfer scenarios.

### Dual-Channel Mode for Enhanced Performance

With its dual-channel operation mode, the BIWIN UFS 2.2 doubles the bandwidth at the same clock frequency, greatly enhancing I/O performance. This is especially effective for multitasking and parallel processing, boosting system responsiveness and overall fluidity.

### Improved Write Performance for Faster Response

Featuring WriteBooster technology, the BIWIN UFS 2.2 optimizes write performance, significantly accelerating data write speeds. This results in faster device responses, enhancing the overall user experience.

### Large Capacity

The BIWIN UFS 2.2 is available in capacities up to 512 GB, providing ample space to store large amounts of data. Its high capacity supports seamless performance in scenarios that demand large-scale data storage and rapid access.

## Technologies

Write Protection

Quick Erase

Wear Leveling

Garbage Collection

TRIM Command

## Applications



Mobile Phone



Tablet



Laptop



Drone



VR / AR

## Specifications

<b>Model Name</b>	UFS
<b>Interface</b>	UFS 2.2
<b>Capacity</b>	64 GB / 128 GB / 256 GB / 512 GB
<b>Sequential Read (Up to)</b>	1000 MB/s
<b>Sequential Write (Up to)</b>	800 MB/s
<b>Operating Voltage</b>	V <sub>cc</sub> = 2.7 V - 3.6 V V <sub>ccq</sub> = 1.7 V - 1.95 V
<b>Dimensions</b>	11.50 × 13.00 mm
<b>Packaging</b>	FBGA 153 Ball
<b>Operating Temperature</b>	-25°C to + 85°C
<b>Storage Temperature</b>	-40°C to + 85°C
<b>Supported Platforms</b>	Mediatek, Unisoc, Qualcomm, Rockchip
<b>Warranty</b>	3-Year Limited

## Order Information

Capacity	Part Number	Packaging	Dimensions
<b>64 GB</b>	BWU2A0516B064G	FBGA153	11.50 × 13.00 mm
<b>128 GB</b>	BWU2A0526B128G	FBGA153	11.50 × 13.00 mm
<b>256 GB</b>	BWU2A0546B256G	FBGA153	11.50 × 13.00 mm
<b>512 GB</b>	BWU2ANY46B512G	FBGA153	11.50 × 13.00 mm

1. Tested by BIWIN labs. Actual performance may vary due to systems, devices, or environment.
2. Maintenance and future updates are required throughout the product lifecycle. Specifications are subject to change without notice.
3. The pictures are for illustration only. Actual products may vary due to product enhancements or changes.
4. Not all products are sold in all regions of the world.
5. Please visit [www.biwintech.com](http://www.biwintech.com) for warranty details in your region.
6. For more information, please contact [sales@biwintech.com](mailto:sales@biwintech.com).

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